

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10690782			
<b>Filing Date:</b>	21-Oct-2003			
<b>Title of Invention:</b>	METHOD FOR MANUFACTURING A WAFER LEVEL CHIP SCALE PACKAGE			
<b>First Named Inventor/Applicant Name:</b>	Jin-Hyuk Lee			
<b>Filer:</b>	Hosoon Lee/Stormi Davis			
<b>Attorney Docket Number:</b>	9903-071			
Filed as Large Entity				
<b>Utility      Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
Utility Appt Issue fee	1501	1	1400	1400
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1700